

# TRASKBRITT

Intellectual Property Attorneys

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Ed Kirchmeier  
Micron Technology, Inc.  
Mailstop 525  
8000 South Federal Way  
Boise, ID 83707-0006

Re: U.S. PATENT APPLICATION

<b>Invention</b>	LEADLESS PACKAGING FOR IMAGE SENSOR DEVICES AND METHODS OF ASSEMBLY
<b>Inventor</b>	Boon et al.
<b>Assignee</b>	Micron Technology, Inc.
<b>Application No.</b>	10/693,376
<b>Filing Date</b>	October 23, 2003
<b>Your Ref No.</b>	02-0240.01/US
<b>Our Case No.</b>	2269-5353.1US

Dear Ed:

Enclosed is a copy of a Supplemental Information Disclosure Statement for the U.S. Patent application identified above which was filed today in the U.S. Patent and Trademark Office. We will notify you of further actions issued by the Patent Office as we receive them.

If you have any questions, please do not hesitate to contact me.

Very truly yours,

Shawnee L. MacDonald  
Legal Staff Assistant

KLD/dp:slm

Document in ProLaw

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THE PATENT & TRADEMARK OFFICE MAILROOM DATE  
STAMPED HEREON IS AN ACKNOWLEDGEMENT THAT ON THIS  
DATE THE PATENT & TRADEMARK OFFICE RECEIVED

Supplemental Information Disclosure Statement (2 pages),  
Form PTO/SB/08A (1 page).

Invention: LEADLESS PACKAGING FOR IMAGE SENSOR  
DEVICES AND METHODS OF ASSEMBLY  
Applicant(s): Boon et al.  
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